

a connector body having a receiving part that extends along the front side of the module being in a connection position, and a groove provided in a rear face thereof into which the front side of the module is inserted, said groove having contacts provided therein which contact the conductive pad on both a top surface and a bottom surface of the module when the module is placed in an insertion/withdrawal position while allowing the pad to shift in a direction of insertion/withdrawal when the module is in the insertion/withdrawal position in which the rear side of the module is at a higher level than in the connection position, and a pair of lateral supporting parts that extend from the receiving part to support a left side, a right side and a bottom of the module in the connection position; and

a metallic cover including a first connection means for pivotably connecting said metallic cover to said receiving part of said connector body and a second connection means for connection to said lateral supporting parts, said metallic cover adapted to engage the connector body to sandwich the module between said metallic cover and the supporting part to thereby maintain the module in the connection position,

wherein said lateral supporting parts each include a stepped part formed on an inner side thereof for supporting the side and bottom faces of the module, and a slotted portion formed on an outer side thereof for receiving said second connection means of said metallic cover.

20. (Thrice Amended) A connector for a module having a semiconductor chip mounted

on a rectangular board and a conductive pad on a front side of the board, the connector connecting the module to a printed circuit board in a position wherein a plane of the board is substantially

parallel to the printed circuit board, said connector comprising:

a connector body having a receiving part that extends along the front side of the module being in a connection position, and a groove provided in a rear face thereof into which the front side of the module is inserted, said groove having contacts provided therein which contact the conductive pad on both a top surface and a bottom surface of the module when the module is placed in an insertion/withdrawal position while allowing the pad to shift in a direction of insertion/withdrawal when the module is in the insertion/withdrawal position in which the rear side of the module is at a higher level than in the connection position, and a pair of supporting parts that extend from the receiving part to support a left side, a right side and a bottom of the module in the connection position;

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a metallic cover that is adaptable to engage with the connector body to sandwich the module between said metallic cover and the supporting parts to thereby maintain the module in the connection position, said metallic cover including a window for exposing the semiconductor chip when the module is placed in the connection position, and a heat sink secured to said metallic cover and contacts the semiconductor chip to dissipate heat therefrom, at least one of said metallic cover and said heat sink covering said contacts and the conductive pad to exhibit a shielding function against electromagnetic waves,

wherein said supporting parts each include a stepped part formed on an inner side thereof for supporting side and bottom faces of the module, and a slotted portion formed on an outer side thereof for receiving said metallic cover.

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